

ABSTRACT

In this process for the reflow soldering of electronic components (22) to a substrate, for example a printed-circuit board (20), solder alloy is used on the substrate (20) at some of the points of connection to the components (22), the components are placed at the points of connection and a soldering operation proper is carried out on the components (22) by heat treatment of the substrate, by bringing it into contact with a treatment atmosphere at a pressure close to atmospheric pressure, the said treatment atmosphere containing excited or unstable chemical species and being substantially free of electrically charged species, the atmosphere being obtained by passing an initial treatment gas through an electrical discharge, and the heat treatment of the substrate being obtained by means of the chemical species thus heated under the action of the discharge.

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Figure 1 to be reproduced.